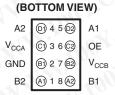
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TXS0102 2-BIT BIDIRECTIONAL VOLTAGE-LEVEL TRANSLATOR FOR OPEN-DRAIN APPLICATIONS

SCES640-JANUARY 2007

FEATURES

- Available in the Texas Instruments
 NanoStar[™] and NanoFree[™] Packages
- 1.65 V to 3.6 V on A port and 2.3 V to 5.5 V on B port (V_{CCA} ≤ V_{CCB})
- V_{CC} Isolation Feature If Either V_{CC} Input Is at GND, Both Ports Are in the High-Impedance State
- I_{off} Supports Partial-Power-Down Mode Operation
- Latch-Up Performance Exceeds 100 mA Per JESD 78, Class II
- ESD Protection Exceeds JESD 22
 - A Port
 - 2500-V Human-Body Model (A114-B)
 - 250-V Machine Model (A115-A)
 - 1500-V Charged-Device Model (C101)
 - B Port
 - 8-kV Human-Body Model (A114-B)
 - 250-V Machine Model (A115-A)
 - 1500-V Charged-Device Model (C101)





DESCRIPTION/ORDERING INFORMATION

This two-bit noninverting translator uses two separate configurable power-supply rails. The A port is designed to track V_{CCA} . V_{CCA} accepts any supply voltage from 1.65 V to 3.6 V. The B port is designed to track V_{CCB} . V_{CCA} must be less than or equal to V_{CCB} . V_{CCB} accepts any supply voltage from 2.3 V to 5.5 V. This allows for low-voltage bidirectional translation between any of the 1.8-V, 2.5-V, 3.3-V, and 5-V voltage nodes.

When the output-enable (OE) input is low, all outputs are placed in the high-impedance state.

To ensure the high-impedance state during power up or power down, OE should be tied to GND through a pulldown resistor; the minimum value of the resistor is determined by the current-sourcing capability of the driver.

ORDERING INFORMATION

TA	PACKAGE ⁽¹⁾		ORDERABLE PART NUMBER	TOP-SIDE MARKING(2)
4.3	NanoStar™ – WCSP (DSBGA) 0.23-mm Large Bump – YZP	Reel of 3000	TXS0102YZPR	
-40°C to 85°C	SSOP - DCT	Reel of 3000	TXS0102DCTR	NFEZ
	SSOP - DC1	Tube of 250	TXS0102DCTT	NFEZ
	VSSOP - DCU	Reel of 3000	TXS0102DCUR	NFE

(1) Package drawings, standard packing quantities, thermal data, symbolization, and PCB design guidelines are available at www.ti.com/sc/package.

(2) DCT: The actual top-side marking has three additional characters that designate the year, month, and assembly/test site. DCU: The actual top-side marking has one additional character that designates the assembly/test site. YZP: The actual top-side marking has three preceding characters to denote year, month, and sequence code, and one following character to designate the assembly/test site. Pin 1 identifier indicates solder-bump composition (1 = SnPb, • = Pb-free).



Please be aware that an important notice concerning availability, standard warranty, and use in critical applications of Texas Instruments semiconductor products and disclaimers thereto appears at the end of this data sheet.

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2-BIT BIDIRECTIONAL VOLTAGE-LEVEL TRANSLATOR FOR OPEN-DRAIN APPLICATIONS

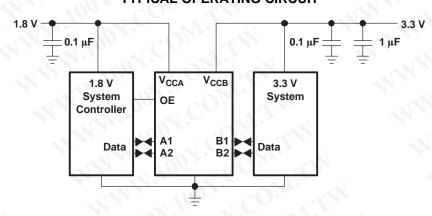
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PIN DESCRIPTION (DCT AND DCU PACKAGES)

NO.	NAME	FUNCTION
1	B2	Input/output B. Referenced to V _{CCB} .
2	GND	Ground
3	V_{CCA}	A-port supply voltage. 1.65 V ≤ V _{CCA} ≤ 3.6 V and V _{CCA} ≤ V _{CCB}
4	A2	Input/output A. Referenced to V _{CCA} .
5	A1	Input/output A. Referenced to V _{CCA} .
6	OE	3-state output mode enable. Pull OE low to place all outputs in 3-state mode. Referenced to V_{CCA} .
7	V _{CCB}	B-port supply voltage. 2.3 V ≤ V _{CCB} ≤ 5.5 V
8	B1	Input/output B. Referenced to V _{CCB} .

TYPICAL OPERATING CIRCUIT





TXS0102 2-BIT BIDIRECTIONAL VOLTAGE-LEVEL TRANSLATOR FOR OPEN-DRAIN APPLICATIONS

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Absolute Maximum Ratings⁽¹⁾

over recommended operating free-air temperature range (unless otherwise noted)

100 (0) (1)	1100	MIN	MAX	UNIT
Supply voltage range		-0.5	4.6	V
Supply voltage range		-0.5	6.5	V
lanut valtaga ranga(2)	A port	-0.5	4.6	V
input voltage range -/	B port	-0.5	6.5	V
Voltage range applied to any output	A port	-0.5	4.6	
in the high-impedance or power-off state (2)	B port	-0.5	6.5	V
Valence and the second	A port	-0.5	V _{CCA} + 0.5	V
voltage range applied to any output in the high or low state (27.67	B port	-0.5	V _{CCB} + 0.5	V
Input clamp current	V _I < 0	1100	-50	mA
Output clamp current	V _O < 0	10	-50	mA
Continuous output current			±50	mA
Continuous current through V _{CCA} , V _{CCB} , or GND			±100	mA
	DCT package		220	
Package thermal impedance ⁽⁴⁾	DCU package	227		°C/W
	YZP package		102	
Storage temperature range		-65	150	°C
	Supply voltage range Input voltage range (2) Voltage range applied to any output in the high-impedance or power-off state (2) Voltage range applied to any output in the high or low state (2)(3) Input clamp current Output clamp current Continuous output current Continuous current through V _{CCA} , V _{CCB} , or GND Package thermal impedance (4)	$\begin{array}{c} \text{Supply voltage range} \\ \text{Input voltage range}^{(2)} & \begin{array}{c} \text{A port} \\ \text{B port} \\ \end{array} \\ \text{Voltage range applied to any output} \\ \text{in the high-impedance or power-off state}^{(2)} & \begin{array}{c} \text{A port} \\ \text{B port} \\ \end{array} \\ \text{Voltage range applied to any output in the high or low state}^{(2)(3)} & \begin{array}{c} \text{A port} \\ \text{B port} \\ \end{array} \\ \text{B port} \\ \end{array} \\ \text{Input clamp current} & \begin{array}{c} \text{V}_{1} < 0 \\ \text{Output clamp current} \\ \end{array} \\ \text{Continuous output current} \\ \text{Continuous current through V}_{\text{CCA}}, \text{V}_{\text{CCB}}, \text{ or GND} \\ \end{array} \\ \begin{array}{c} \text{DCT package} \\ \text{DCU package} \\ \text{YZP package} \\ \end{array}$	$ \begin{array}{c} \text{Supply voltage range} & -0.5 \\ \text{Supply voltage range} & -0.5 \\ \\ \text{Input voltage range}^{(2)} & \begin{array}{c} \text{A port} & -0.5 \\ \text{B port} & -0.5 \\ \\ \text{B port} & -0.5 \\ \\ \text{A port} & -0.5 \\ \\ \text{B port} & -0.5 \\ \\ \text{Continuous current} & V_{\text{I}} < 0 \\ \\ \text{Output clamp current} & V_{\text{O}} < 0 \\ \\ \text{Continuous output current} \\ \\ \text{Continuous output current} \\ \\ \text{Continuous current through V_{CCA}, V_{CCB}, or GND} \\ \\ \text{Package thermal impedance}^{(4)} & \begin{array}{c} D\text{CT package} \\ \\ D\text{CU package} \\ \\ \text{YZP package} \\ \end{array} $	$\begin{array}{c ccccccccccccccccccccccccccccccccccc$

Stresses beyond those listed under "absolute maximum ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under "recommended operating conditions" is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

The input and output negative-voltage ratings may be exceeded if the input and output current ratings are observed. The value of V_{CCA} and V_{CCB} are provided in the recommended operating conditions table.

The package thermal impedance is calculated in accordance with JESD 51-7.

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Recommended Operating Conditions⁽¹⁾⁽²⁾

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No.		1	V _{CCA}	V _{CCB}	MIN	MAX	UNIT
V_{CCA}	Supply voltage ⁽³⁾			100	1.65	3.6	V
V _{CCB}	Supply voltage (9)	W. W			2.3	5.5	V
144	1 D	A-port I/Os	1.65 V to 1.95 V	2.3 V to 5.5 V	V _{CCI} - 0.2	V _{CCI}	
V	Lligh lovel input valtage	A-port I/Os	2.3 V to 3.6 V	2.3 V t0 5.5 V	V _{CCI} - 0.4	V _{CCI}	V
V_{IH}	High-level input voltage	B-port I/Os	1.65 V to 3.6 V	2.2.V to F.F.V	V _{CCI} - 0.4	V _{CCI}	V
		OE input	1.65 V to 3.6 V	2.3 V to 5.5 V	$V_{CCA} \times 0.65$	5.5	
		A-port I/Os	1	W.	0	0.15	-1
V_{IL}	Low-level input voltage	B-port I/Os	1.65 V to 3.6 V 2.3 V to 5.5 V		0	0.15	V
		OE input	1.		0	$V_{CCA} \times 0.35$	
	MAN I	A-port I/Os, push-pull driving	ONITA	W	M. Jon	10	WI
Δt/Δν	Input transition rise or fall rate	B-port I/Os, push-pull driving	1.65 V to 3.6 V	2.3 V to 5.5 V	MAIN	10	ns/V
		Control input				10	
T _A	Operating free-air tempe	rature		. 1	-40	85	°C

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⁽¹⁾ (2) (3)

 V_{CCI} is the supply voltage associated with the input port. V_{CCO} is the supply voltage associated with the output port. V_{CCA} must be less than or equal to V_{CCB} , and V_{CCA} must not exceed 3.6 V.



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Electrical Characteristics (1)(2)(3)

over recommended operating free-air temperature range (unless otherwise noted)

D	ARAMETER	TEST			$T_A = 25^{\circ}C$	-40°C to 85°C	UNIT
P/	ARAIVIETER	CONDITIONS	V _{CCA}	V _{CCB}	MIN TYP MAX	MIN MAX	UNIT
		$I_{OH} = -20 \mu A,$ $V_{IB} \ge V_{CCB} - 0.4 \text{ V}$ 1.65 V to 3.6 V		2.3 V to 5.5 V V _{CCA} × 0.67	V _{CCA} × 0.67	V	
V _{OLA}		$I_{OL} = 1 \text{ mA},$ $V_{IB} \le 0.15 \text{ V}$	1.65 V to 3.6 V	2.3 V to 5.5 V	131.100	0.4	V
V _{OHB}	NN	$\begin{split} I_{OH} &= -20 \; \mu\text{A}, \\ V_{IA} &\geq V_{CCA} - 0.2 \; V \end{split}$	1.65 V to 3.6 V	2.3 V to 5.5 V	11.100	V _{CCB} × 0.67	V
V_{OLB}	MW.	$I_{OL} = 1 \text{ mA},$ $V_{IA} \le 0.15 \text{ V}$	1.65 V to 3.6 V	2.3 V to 5.5 V	11/1/10	0.4	V
I _I	OE	1,100	1.65 V to 5.5 V	1.65 V to 5.5 V	±1	±2	μΑ
	A port		0 V	0 to 5.5 V	±1	±2	μА
I _{off}	B port	1100	0 to 3.6 V	0 V	±1	±2	μА
loz	A or B port		1.65 V to 5.5 V	2.3 V to 5.5 V	±1	±2	μΑ
			1.65 V to V _{CCB}	2.3 V to 5.5 V		2.4	
I_{CCA}		$V_I = V_O = open,$ $I_O = 0$	3.6 V	0 V		2.2	μΑ
		10 - 0	0 V	5.5 V		-1	
	1		1.65 V to V _{CCB}	2.3 V to 5.5 V		12	
I _{CCB}		$V_I = V_O = open,$ $I_O = 0$	3.6 V	0 V		-1	μΑ
		10 - 0	0 V	5.5 V			
I _{CCA} +	- I _{CCB}	$V_I = V_{CCI}$ or GND, $I_O = 0$	1.65 V to V _{CCB}	2.3 V to 5.5 V	N	14.4	μΑ
CI	OE		3.3 V	3.3 V	2.5	3.5	pF
,	A or B port		3.3 V	3.3 V	10		1 100
Cio	A port			3.	5	6	pF
	B port		1130	₂ 1 C	6	7.5	

Timing Requirements

over recommended operating free-air temperature range, V_{CCA} = 1.8 V \pm 0.15 V (unless otherwise noted)

70	A CO		MIN THE	V _{CCB} = ± 0.2	2.5 V ! V	V _{CC} = 3 ± 0.3	V_{CC} = 3.3 V \pm 0.3 V		V _{CC} = 5 V ± 0.5 V	
. 1			MIN I		MIN MAX MI		MAX	MIN	MAX	
W.	D. (1)	Push-pull driving			21		22	~ 1	24	N.41
	Data rate	Open-drain driving		110	1	CO	1		1	Mbps
	Dulas duration	Push-pull driving	Data inputa	47		45	100	41		
ı _w	Pulse duration	Open-drain driving Data inputs		500	100	500		500		ns

Timing Requirements

over recommended operating free-air temperature range, V_{CCA} = 2.5 V ± 0.2 V (unless otherwise noted)

	MAN. 1001. COMP. CAN			V _{CCB} = ± 0.2	2.5 V V	V _{CC} = 3 ± 0.3	3.3 V V	V _{CC} = ± 0.5	5 V 5 V	UNIT
				MIN MAX MIN MAX		MIN	MIN MAX			
	Data	Push-pull driving			20	-11	22	, dQ	24	Mana
	Data rate	Open-drain driving			1	M.	1		1	Mbps
	Dulas duration	Push-pull driving	Data insute	50		45	100	41		
ι _w	, Pulse duration	Open-drain driving	Data inputs	500		500	. 0	500	40	ns

 V_{CCI} is the V_{CC} associated with the input port. V_{CCO} is the V_{CC} associated with the output port. V_{CCA} must be less than or equal to V_{CCB} , and V_{CCA} must not exceed 3.6 V.

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Timing Requirements

over recommended operating free-air temperature range, V_{CCA} = 3 V \pm 0.3 V (unless otherwise noted)

1 100 N.C	WW.W.	V _{CC} = 3 ± 0.3	3.3 V V	V _{CC} = ± 0.5	UNIT		
100			MIN	MAX	MIN	MAX	
Data mata	Push-pull driving			23		24	Mhaa
Data rate	Open-drain driving		1 100	1	O.	1	Mbps
t Dules duration	Push-pull driving	Data inputa	43		41	1.	A
Pulse duration	Open-drain driving	Data inputs	500	×1	500		ns

Switching Characteristics

over recommended operating free-air temperature range, V_{CCA} = 1.8 V \pm 0.15 V (unless otherwise noted)

PARAMETER	FROM (INPUT)	TO (OUTPUT)	TEST	V _{CCB} = ± 0.	= 2.5 V .2 V	V _{CCB} :	= 3.3 V .3 V	V _{CCB} ± 0.	= 5 V 5 V	UNIT
	(INPUT)	(001101)	CONDITIONS		MAX	MIN MAX		MIN MAX		
. <	100	-1 CO	Push-pull driving		5.3		5.4		6.8	J >
t _{PHL}	^	В	Open-drain driving	2.3	8.8	2.4	9.6	2.6	10	ns
	^		Push-pull driving		6.8		7.1		7.5	115
t _{PLH}			Open-drain driving	45	260	36	208	27	198	~(
			Push-pull driving		4.4		4.5		4.7	1.0
t _{PHL}	D	1100	Open-drain driving	1.9	5.3	1.1	4.4	1.2	4	no
•	В	A	Push-pull driving	1	5.3		4.5	W.	0.5	ns
t _{PLH}			Open-drain driving	45	175	36	140	27	102	
t _{en}	OE	A or B			200		200		200	ns
t _{dis}	OE	A or B		1	50		40		35	ns
10 h	A-port ris	o timo	Push-pull driving	3.2	9.5	2.3	9.3	2	7.6	na
t _{rA}	A-port ris	e time	Open-drain driving	38	165	30	132	22	95	ns
	D nort rio	a tima	Push-pull driving	4	10.8	2.7	9.1	2.7	7.6	200
t _{rB}	B-port ris	e time	Open-drain driving	34	145	23	106	10	58	ns
100, 1	A-port fa	II timo	Push-pull driving	2	5.9	1.9	6	1.7	13.3	
t _{fA}	A-port la	ii ume	Open-drain driving	4.4	6.9	4.3	6.4	4.2	6.1	200
1.0	P nort fo	II timo	Push-pull driving	2.9	13.8	2.8	16.2	2.8	16.2	ns
t _{fB}	B-port fa	ii uiiie	Open-drain driving	6.9	13.8	7.5	16.2	7	16.2	
t _{SK(O)}	Channel-to-ch	annel skew			0.7		0.7		0.7	ns
May data rata	Push-pull di	Push-pull driving	21	10)	22		24		Mbrz	
Max data rate			Open-drain driving	1		1		1 1		Mbps

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Switching Characteristics

over recommended operating free-air temperature range, V_{CCA} = 2.5 V \pm 0.2 V (unless otherwise noted)

PARAMETER	FROM (INPUT)	TO (OUTPUT)	TEST CONDITIONS	V _{CCB} = ± 0.	= 2.5 V .2 V	V _{CCB} =	= 3.3 V .3 V	V _{CCB}	= 5 V .5 V	UNIT
11, 100.	(INFOI)	(001701)	CONDITIONS	MIN MAX		MIN MAX		MIN MAX		
			Push-pull driving	10.	3.2		3.7		3.8	
t _{PHL}	<1 (1)	В	Open-drain driving	1.7	6.3	2	6	2.1	5.8	ns
1			Push-pull driving	M.	3.5		4.1	Mr.	4.4	113
t _{PLH}	41 0		Open-drain driving	43	250	36	206	27	190	
• < 1		OBRE	Push-pull driving		3		3.6		4.3	
t _{PHL}	В		Open-drain driving	1.8	4.7	2.6	4.2	1.2	4	ns
			Push-pull driving		2.5	. 40	1.6		1	115
t _{PLH}	M. all		Open-drain driving	44	170	37	140	27	103	
t _{en}	OE	A or B			200	_11	200	4 (200	ns
t _{dis}	OE	A or B	· N		50		40		35	ns
	A-port	rise time	Push-pull driving	2.8	7.4	2.6	6.6	1.8	5.6	ns
t _{rA}	A-poit	rise time	Open-drain driving	34	149	28	121	24	89	113
≪1 t -	R-port	rise time	Push-pull driving	3.2	8.3	2.9	7.2	2.4	6.1	ns
t _{rB}	Б-роп	rise time	Open-drain driving	35	151	24	112	12	64	113
	A port	fall time	Push-pull driving	1.9	5.7	1.9	5.5	1.8	5.3	ns
t _{fA}	д-роп	Tall time	Open-drain driving	4.4	6.9	4.3	6.2	4.2	5.8	119
	P nort	fall time	Push-pull driving	2.2	7.8	2.4	6.7	2.6	6.6	ns
t_fB	Б-роп	Tall time	Open-drain driving	5.1	8.8	5.4	9.4	5.4	10.4	113
t _{SK(O)}	Channel-to-	channel skew	A. "ON."		0.7		0.7		0.7	ns
Max data rate	11, 21, 10,	Push-pull driving	20	4	22		24		Mbps	
iviax uala iale			Open-drain driving	1	N	1		1		Mbps

2-BIT BIDIRECTIONAL VOLTAGE-LEVEL TRANSLATOR FOR OPEN-DRAIN APPLICATIONS



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Switching Characteristics

over recommended operating free-air temperature range, V_{CCA} = 3.3 V \pm 0.3 V (unless otherwise noted)

PARAMETER	FROM	TO (OUTPUT)	TEST CONDITIONS	V _{CCB} = ± 0.3	3.3 V 3 V	V _{CCB} ± 0.	= 5 V 5 V	UNIT
11, 100	(INPUT)	(001701)	CONDITIONS	MIN	MAX	MIN	MAX	
N. O.			Push-pull driving		2.4		3.1	
t _{PHL}		В	Open-drain driving	1.3	4.2	1.4	4.6	ns
1	^		Push-pull driving		4.2		4.4	115
t _{PLH}			Open-drain driving	36	204	28	165	
41.5	0.0 0.0 0.0		Push-pull driving	.00	2.5		3.3	
t _{PHL}	В	A	Open-drain driving	1	124	1	97	ns
	1100p		Push-pull driving	40	2.5		2.6	115
t _{PLH}			Open-drain driving	3	139	3	105	
t _{en}	OE	A or B		1	200		200	ns
t _{dis}	OE	A or B			40		35	ns
	A-port rise	timo	Push-pull driving	2.3	5.6	1.9	4.8	ns
t _{rA}	A-port rise	e time	Open-drain driving	25	116	19	85	2
-1 t-	B-port rise	a time	Push-pull driving	2.5	6.4	2.1	7.4	ns
t _{rB}	B-port rise	e time	Open-drain driving	26	116	14	72	115
	A-port fal	Ltimo	Push-pull driving	2	5.4	1.9	5	ns
t _{fA}	A-port rai	Tillie	Open-drain driving	4.3	6.1	4.2	5.7	10
•	B-port fal	Ltimo	Push-pull driving	2.3	7.4	2.4	7.6	ns
t _{fB}	Б -роп таг	i tillie	Open-drain driving	5	7.6	4.8	8.3	115
t _{SK(O)}	Channel-to-cha	annel skew			0.7		0.7	ns
Max data rate		V.7.	Push-pull driving	23		24		Mbss
iviax uala fale		1, 100,	Open-drain driving	1		1	144	Mbps

PRINCIPLES OF OPERATION

Applications

The TXS0102 can be used in level-translation applications for interfacing devices or systems operating at different interface voltages with one another. The TXS0102 is ideal for use in applications where an open-drain driver is connected to the data I/Os. The TXS0102 can also be used in applications where a push-pull driver is connected to the data I/Os, but the TXB0102 might be a better option for such push-pull applications.

Architecture

The TXS0102 architecture (see Figure 1) does not require a direction-control signal to control the direction of data flow from A to B or from B to A.

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PRINCIPLES OF OPERATION (continued)

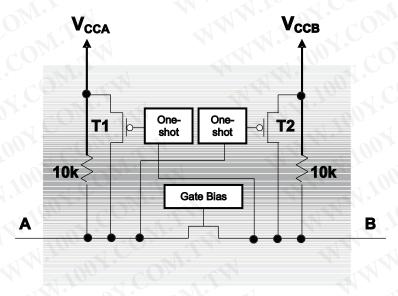


Figure 1. Architecture of a TXS01xx Cell

Each A-port I/O has an internal 10-k Ω pullup resistor to V_{CCA} , and each B-port I/O has an internal 10-k Ω pullup resistor to V_{CCB} . The output one-shots detect rising edges on the A or B ports. During a rising edge, the one-shot turns on the PMOS transistors (T1,T2) for a short duration, which speeds up the low-to-high transition.

Input Driver Requirements

The fall time (t_{fA} , t_{fB}) of a signal depends on the output impedance of the external device driving the data I/Os of the TXS0102. Similarly, the t_{PHL} and max data rates also depend on the output impedance of the external driver. The values for t_{fA} , t_{fB} , t_{PHL} , and maximum data rates in the data sheet assume that the output impedance of the external driver is less than 50 Ω .

Power Up

During operation, ensure that $V_{CCA} \le V_{CCB}$ at all times. During power-up sequencing, $V_{CCA} \ge V_{CCB}$ does not damage the device, so any power supply can be ramped up first.

Enable and Disable

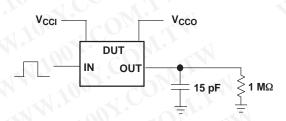
The TXS0102 has an OE input that is used to disable the device by setting OE low, which places all I/Os in the Hi-Z state. The disable time (t_{dis}) indicates the delay between the time when OE goes low and when the outputs actually get disabled (Hi-Z). The enable time (t_{en}) indicates the amount of time the user must allow for the one-shot circuitry to become operational after OE is taken high.

Pullup or Pulldown Resistors on I/O Lines

Each A-port I/O has an internal 10-k Ω pullup resistor to V_{CCA} , and each B-port I/O has an internal 10-k Ω pullup resistor to V_{CCB} . If a smaller value of pullup resistor is required, an external resistor must be added from the I/O to V_{CCA} or V_{CCB} (in parallel with the internal 10-k Ω resistors).



PARAMETER MEASUREMENT INFORMATION



V_{CCO}

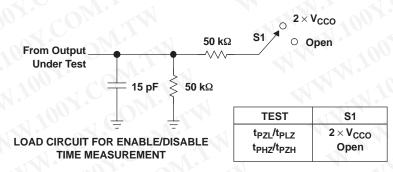
DUT

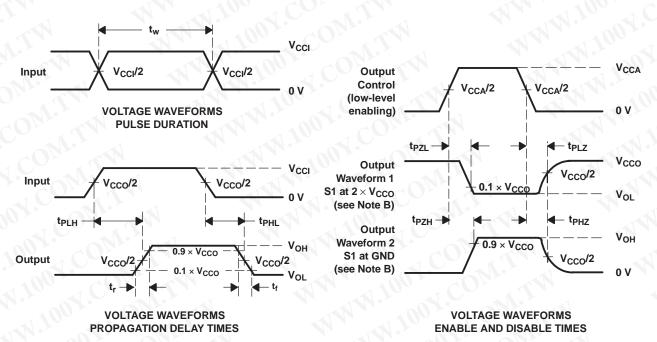
IN OUT

15 pF 1 MΩ

DATA RATE, PULSE DURATION, PROPAGATION DELAY,
OUTPUT RISE AND FALL TIME MEASUREMENT USING
A PUSH-PULL DRIVER

DATA RATE, PULSE DURATION, PROPAGATION DELAY,
OUTPUT RISE AND FALL TIME MEASUREMENT USING
AN OPEN-DRAIN DRIVER





NOTES: A. C_L includes probe and jig capacitance.

- B. Waveform 1 is for an output with internal conditions such that the output is low, except when disabled by the output control. Waveform 2 is for an output with internal conditions such that the output is high, except when disabled by the output control.
- C. All input pulses are supplied by generators having the following characteristics: PRR \leq 10 MHz, $Z_0 = 50 \Omega$, dv/dt \geq 1 V/ns.
- D. The outputs are measured one at a time, with one transition per measurement.
- E. t_{PLZ} and t_{PHZ} are the same as t_{dis}.
- F. t_{PZL} and t_{PZH} are the same as t_{en}.
- G. t_{PLH} and t_{PHL} are the same as t_{pd}.
- H. V_{CCI} is the V_{CC} associated with the input port.
- I. V_{CCO} is the V_{CC} associated with the output port.
- J. All parameters and waveforms are not applicable to all devices.

Figure 2. Load Circuit and Voltage Waveforms





ti.com 5-Feb-2007

PACKAGING INFORMATION

Orderable Device	Status (1)	Package Type	Package Drawing	Pins Package Qty	e Eco Plan ⁽²⁾	Lead/Ball Finish	MSL Peak Temp ⁽³⁾
TXS0102DCUR	ACTIVE	US8	DCU	8 3000	Green (RoHS & no Sb/Br)	k CU NIPDAU	Level-1-260C-UNLIM

⁽¹⁾ The marketing status values are defined as follows:

ACTIVE: Product device recommended for new designs.

LIFEBUY: TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.

NRND: Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.

PREVIEW: Device has been announced but is not in production. Samples may or may not be available.

OBSOLETE: TI has discontinued the production of the device.

(2) Eco Plan - The planned eco-friendly classification: Pb-Free (RoHS), Pb-Free (RoHS Exempt), or Green (RoHS & no Sb/Br) - please check http://www.ti.com/productcontent for the latest availability information and additional product content details.

TBD: The Pb-Free/Green conversion plan has not been defined.

Pb-Free (RoHS): TI's terms "Lead-Free" or "Pb-Free" mean semiconductor products that are compatible with the current RoHS requirements for all 6 substances, including the requirement that lead not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, TI Pb-Free products are suitable for use in specified lead-free processes.

Pb-Free (RoHS Exempt): This component has a RoHS exemption for either 1) lead-based flip-chip solder bumps used between the die and package, or 2) lead-based die adhesive used between the die and leadframe. The component is otherwise considered Pb-Free (RoHS compatible) as defined above.

Green (RoHS & no Sb/Br): TI defines "Green" to mean Pb-Free (RoHS compatible), and free of Bromine (Br) and Antimony (Sb) based flame retardants (Br or Sb do not exceed 0.1% by weight in homogeneous material)

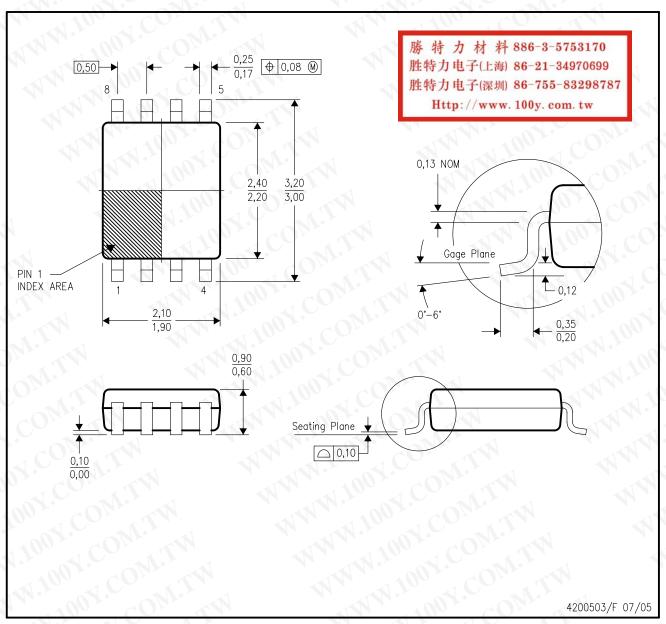
(3) MSL, Peak Temp. -- The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.

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DCU (R-PDSO-G8)

PLASTIC SMALL-OUTLINE PACKAGE (DIE DOWN)



NOTES:

- A. All linear dimensions are in millimeters.
- B. This drawing is subject to change without notice.
- C. Body dimensions do not include mold flash or protrusion. Mold flash and protrusion shall not exceed 0.15 per side.
- D. Falls within JEDEC MO-187 variation CA



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